External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Lead Dioxide (PbO2)	1309-60-0	0	0.93	0.04
	Doped silicon	Silicon (Si)	7440-21-3	0.3	99.07	4.56
			Subtotal	0.3	100	4.6
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.16
	Lead alloy	Silver (Ag)	7440-22-4	0.01	2.5	0.08
	Lead alloy	Lead (Pb)	7439-92-1	0.2	92.5	2.95
			Subtotal	0.22	100	3.19
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.54	100.0	8.16
			Subtotal	0.54	100	8.16
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.34	100.0	5.17
			Subtotal	0.34	100	5.17
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.15
	Pure metal layer	Zinc (Zn)	7440-66-6	0.01	0.02	0.1
	Pure metal layer	Tin (Sn)	7440-31-5	0.01	0.03	0.15
	Pure metal layer	Iron (Fe)	7439-89-6	0.04	0.11	0.54
	Pure metal layer	Copper (Cu)	7440-50-8	32.39	99.81	488.86
			Subtotal	32.46	100	489.8
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.31	5.0	49.92
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	9.92	15.0	149.77
	Filler	Silica fused	60676-86-0	2.98	4.5	44.93
	Carbon Black	Carbon black	1333-86-4	0.33	0.5	4.99
	Filler	Misc. Silica compounds (generic)	14808-60-7	49.61	75.0	748.83
			Subtotal	66.15	100	998.44
			Total	100.01	100	1509.36

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